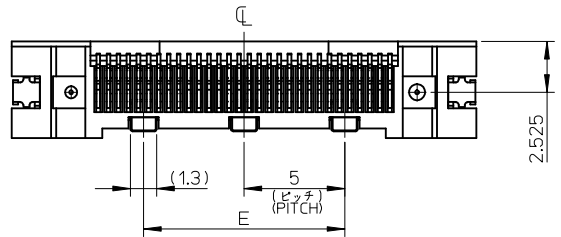
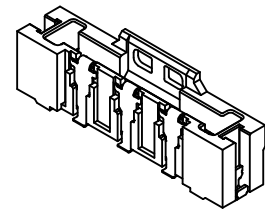
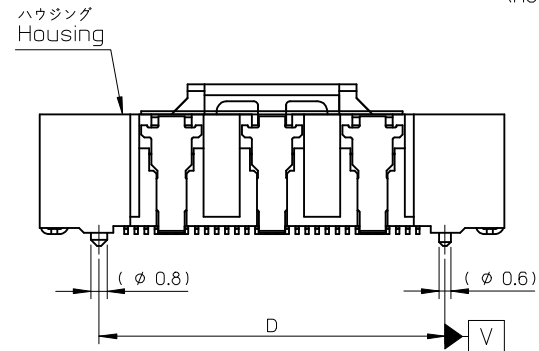
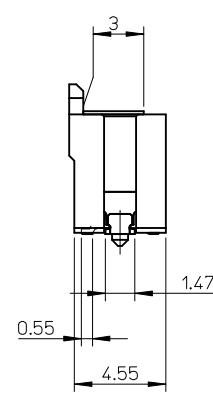
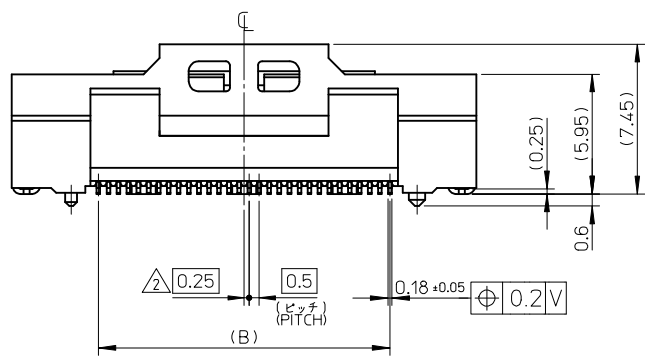


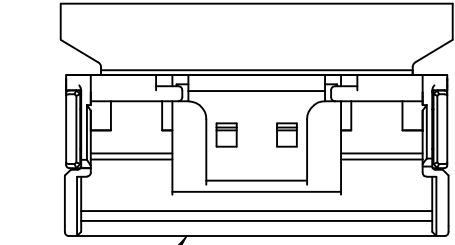
参考基板レイアウト
P.C. BOARD PATTERN
DIMENSION (REF.)
(マウント面)
(MOUNTING SIDE)



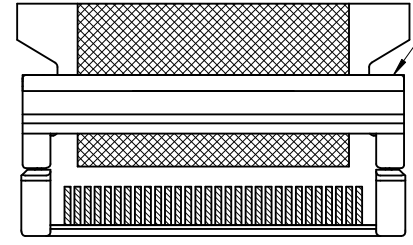
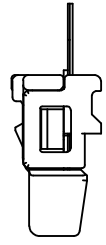
3	10	17.2	19.1	14.5	23.1	501786-3091	30
QTY of Ground Term	E	D	C	B	A	EMBOSSED TAPE PKG.	極数 CIRCUIT
						ORDER No. オーダー番号	

CONNECTOR SERIES No. 501786-***31

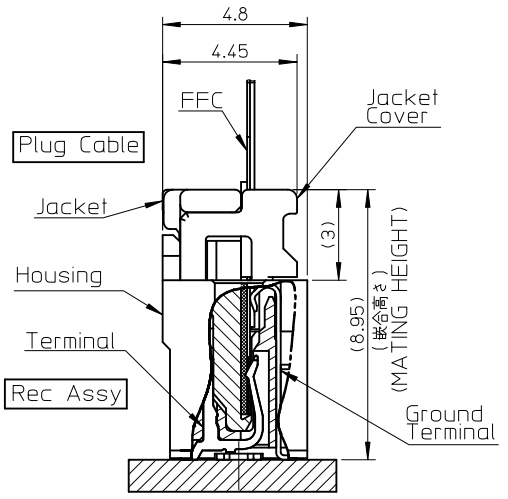
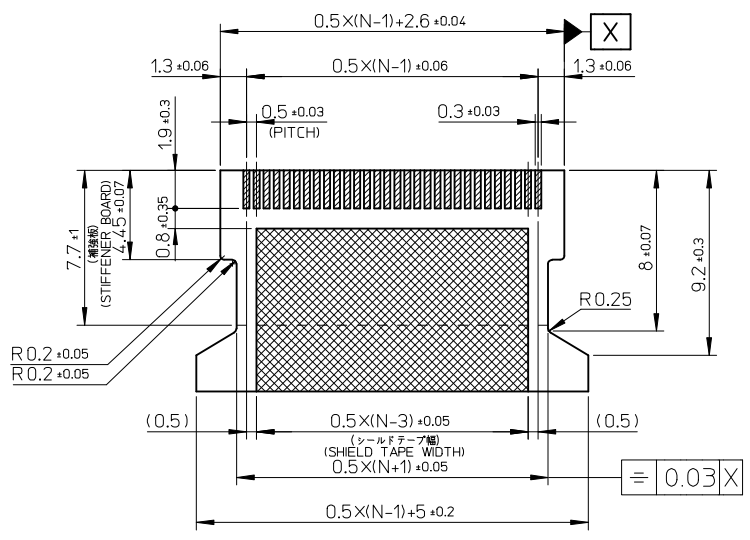
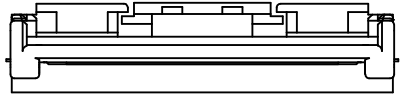
REVISED EC NO: J2010-0779 DRWN: NIISHI 2009/10/19 CHKD: MATSUURA 2009/10/19 APPR: MORIKAWA 2009/10/19	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY H. IJIMA	DATE 07/12/25	TITLE 0.5 FFC TO BOARD CONN REC HSG ASSY(ST)		
	10 OVER 30 UNDER	±0.25	CHECKED BY K. MORIKAWA	DATE 07/12/25	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY H. HIRATA	DATE 07/12/25	DOCUMENT NO. SD-501786-008		
	ANGULAR ±1 °		MATERIAL NO. SEE CHART		SHEET NO. 1 OF 2		
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		



④ ジャケット JACKET



⑤ ジャケットカバー JACKET COVER



嵌合断面図 MATED CONNECTOR SECTION

注記 NOTE

1. 使用材料 MATERIAL
 - ハウジング HOUSING : 液晶ポリマー (LCP), ガラス充填, UL94V-0 色: 黒色
 - ターミナル TERMINAL : 燐青銅 (t=0.18)
 - メッキ PLATING : 燐青銅 (t=0.18)
 - CONTACT AREA : ニッケル下地 (1.0 μm以上) 金メッキ (0.1 μm以上) OVER NICKEL PLATING (1.0 μm MINIMUM) GOLD PLATING (0.1 μm MINIMUM)
 - ソルダーテール SOLDER TAIL : ニッケル下地 金メッキ
 - TAIL AREA : OVER NICKEL PLATING GOLD PLATING
 - 金具 FITTING NAIL : 燐青銅 (t=0.25)
 - グラウンド端子 GROUND TERMINAL : ニッケル下地 錫メッキ (1.0 μm以上) PHOSPHOR BRONZE (t=0.15) TIN OVER NICKEL PLATING (1.0 μm MINIMUM)

- N=偶数に適用 (N:極数) APPLY FOR N-EVEN(CIRCUIT)
- ③ パターン剥離止め用金具 FITTING NAIL FOR PREVENTION OF PEELING OF P.C.B PATTERN.
 - ④ 適合ジャケット : 501783-**09 製品詳細寸法はSD-501783-004を参照下さい。 RE DETAILED DIMENTION,SEE SD-501783-004.
 - ⑤ 適合ジャケットカバー : 501784-**08. 製品詳細寸法はSD-501784-005を参照下さい。 APPLICABLE JACKET COVER : 501784-**08. RE DETAILED DIMENTION SEE SD-501784-005
6. ELV及びRoHS適合品 ELV AND RoHS COMPLIANT
 7. FFCについて ABOUT FFC
 打ち抜き方向は導体側から補強板側を推奨します。 導体部については軟烙銅35 μmまたは50 μmを推奨します。
 RECOMMENDED PUNCHING DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER SIDE
 RECOMMENDED CONDUCTOR SPEC : SOFT COPPER FOIL
 RECOMMENDED CONDUCTOR THICKNESS : 35MICROMETER OR 50MICROMETER

コネクタ接点部 CONTACT AREA
 シールド部 SHIELD AREA

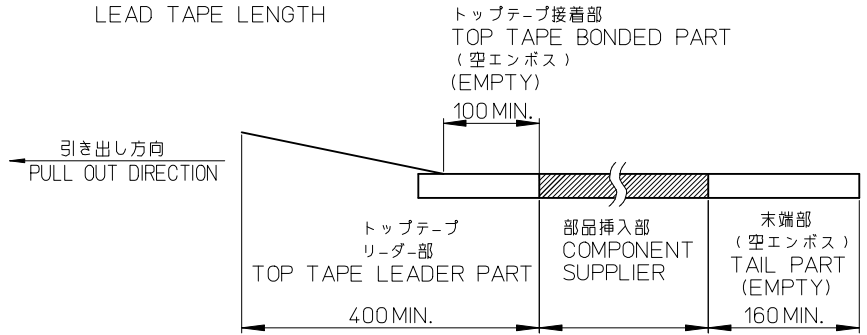
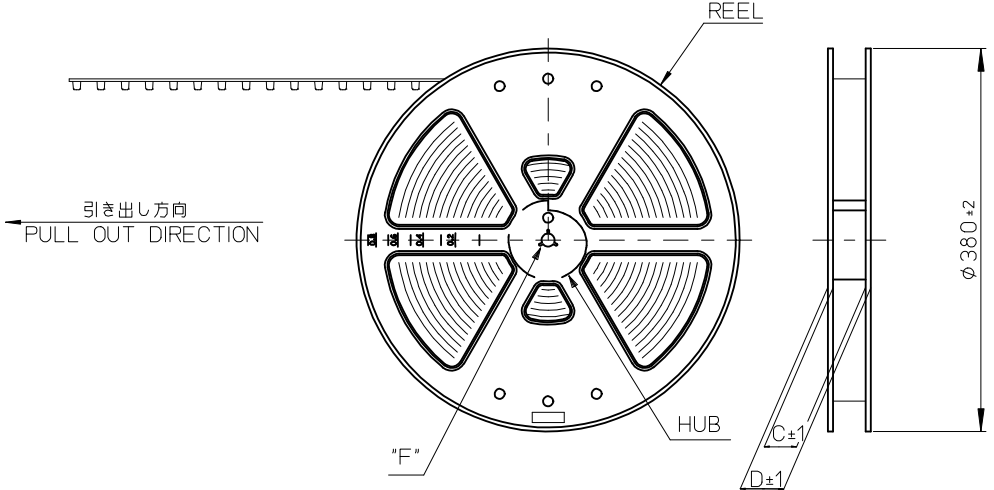
適合する金めっきFFC推奨寸法
 APPLICABLE FFC OF GOLD PLATING RECOMMENDED DIMENSION
 (仕上がり厚さ: コネクタ接点部 0.3 ± 0.03)
 シールド部 0.44 ± 0.05)
 (THICKNESS : CONTACT AREA 0.3 ± 0.03)
 SHIELD AREA 0.44 ± 0.05)

REVISED EC NO: J2010-0779 DRM:NNISHI 2009/10/19 CHKD:WATSUURA 2009/10/19 APPR:KMKR:IKAWA 2009/10/19	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION		
				MM ONLY		≠	METRIC			
		10 UNDER	± 0.2	DRAWN BY	DATE	TITLE				
		10 OVER 30 UNDER	± 0.25	H. IJIMA	07/12/25	0.5 FFC TO BOARD CONN REC HSG ASSY(ST)				
	30 OVER	± 0.3	CHECKED BY	DATE						
			K. MORIKAWA	07/12/25						
			APPROVED BY	DATE						
			H. HIRATA	07/12/25	MOLEX INCORPORATED					
			MATERIAL NO.	DOCUMENT NO.	SEE SHEET 1				SHEET NO.	
					SD-501786-008				2 OF 2	
			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

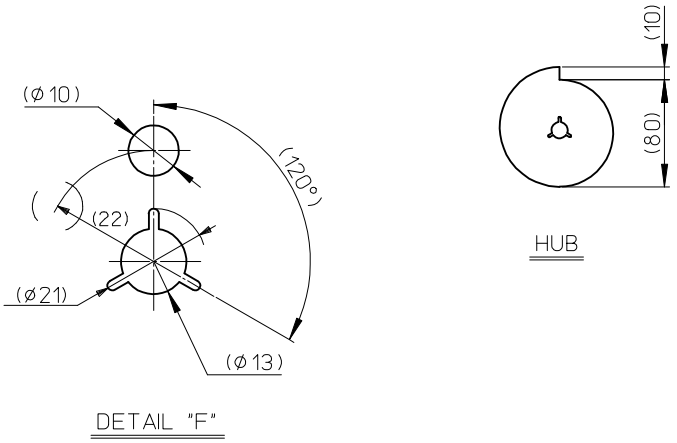
ELV AND RoHS COMPLIANT.

NOTES

1. 梱包数量：900 個/リール
NUMBER OF CONNECTORS:900 PCS/REEL
2. リードテープ長さ
LEAD TAPE LENGTH



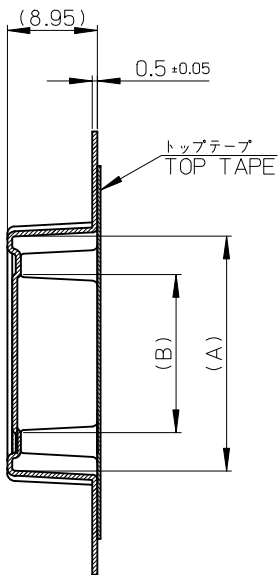
3. 製品詳細寸法については図面 SD-501786-008を参照下さい。
RE DETAILED DIMENSION, SEE SD-501786-008.
4. 材料(MATERIAL)
キャリアテープ(CARRIER TAPE)：ポリスチレン(POLYSTYRENE)
トップテープ(TOP TAPE)：PET, PE, PE
リール(REEL)：ポリスチレン(POLYSTYRENE)<リサイクル材を含む>
<RECYCLE MATERIAL CONTAINED>
5. ELV及びRoHS適合品
ELV AND RoHS COMPLIANT



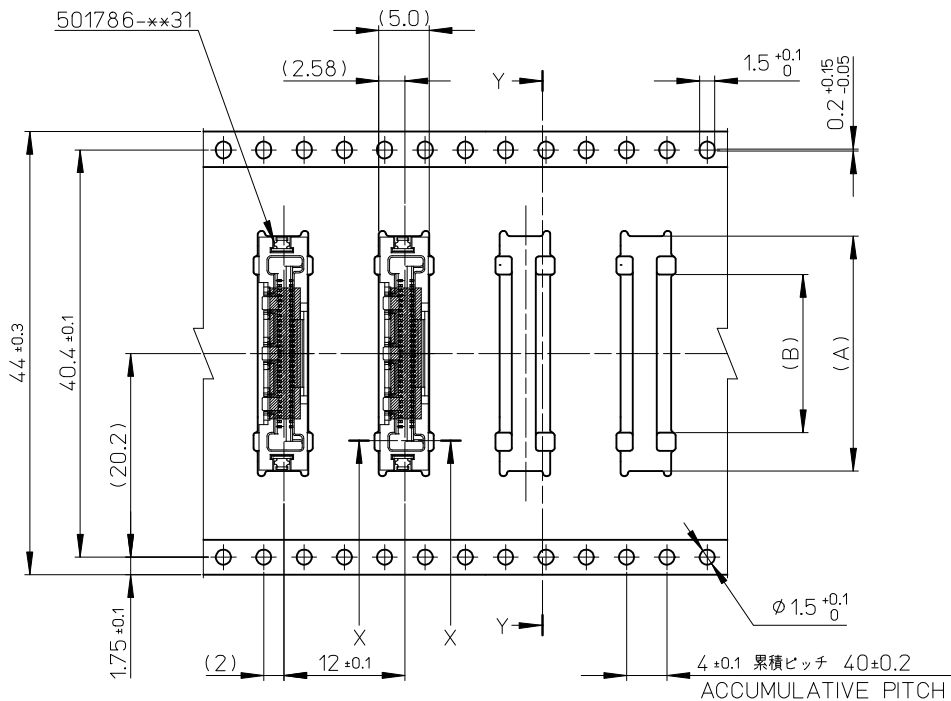
501786-**91 MODEL NO.

REVISED EC NO: J2009-1986 DRWN:YSHIBATA 2009/02/26 CHKD:THARUYAMA 2009/02/26 APPR:NUKITA 2009/02/26 REV A	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY H. IJIMA	DATE 07/12/25	TITLE EMBSTP PKG FOR 0.5 FFC TO BOARD ST TYPE			
	10 OVER 30 UNDER	±0.25	CHECKED BY K. MORIKAWA	DATE 07/12/25	MOLEX INCORPORATED DOCUMENT NO. SD-501786-009 SHEET NO. 1 OF 2			
	30 OVER	±0.3	APPROVED BY H. HIRATA	DATE 07/12/25				
	ANGULAR	±3 °	MATERIAL NO. 501786-**91		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3						

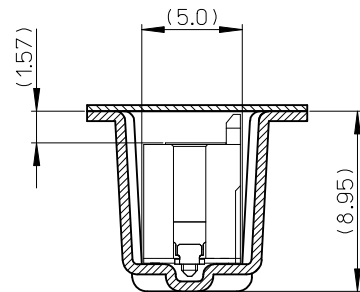
引き出し方向
PULL OUT DIRECTION



SECT. Y-Y



44mm幅キャリアテープ
44mm WIDTH CARRIER TAPE



SECT. X-X

56	61.4	57.4	25.68	33.3	501786-5091	50
44	49.4	45.4	15.68	23.3	501786-3091	30
キャリアテープ幅 CARRIER TAPE WIDTH	D	C	B	A	製品番号 MATERIAL NO.	極数 CKT

REVISED EC NO: J2009-1986 DRWN: YSHIBATA 2009/02/26 CHKD: THARUYAMA 2009/02/26 APPR: NUKITA 2009/02/26 REV A	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		10 UNDER ±0.2	DRAWN BY H. IJIMA	DATE 07/12/25	TITLE EMBSTP PKG FOR 0.5 FFC TO BOARD ST TYPE	
		10 OVER 30 UNDER ±0.25	CHECKED BY K. MORIKAWA	DATE 07/12/25	MOLEX INCORPORATED	
		30 OVER ±0.3	APPROVED BY H. HIRATA	DATE 07/12/25	MATERIAL NO. 501786-**91	DOCUMENT NO. SD-501786-009
		ANGULAR ±3°	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				